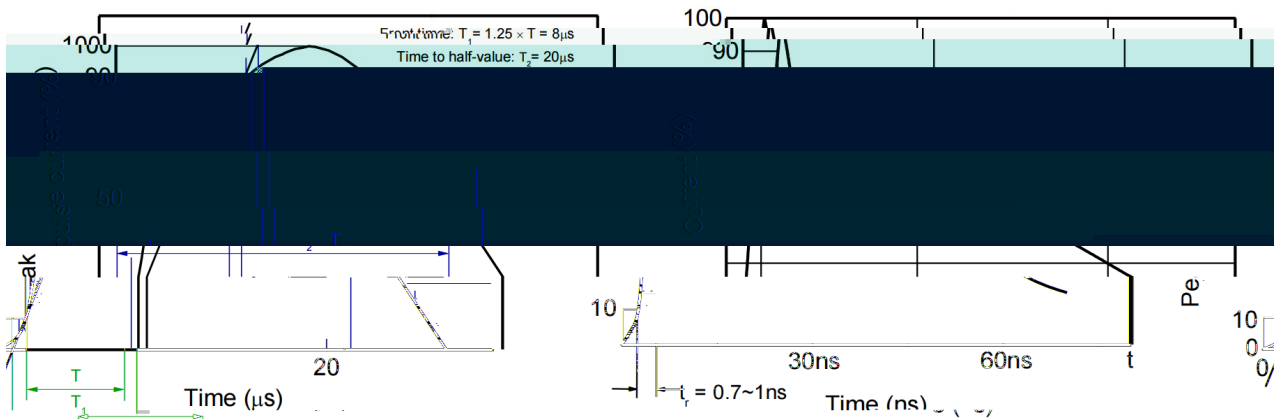




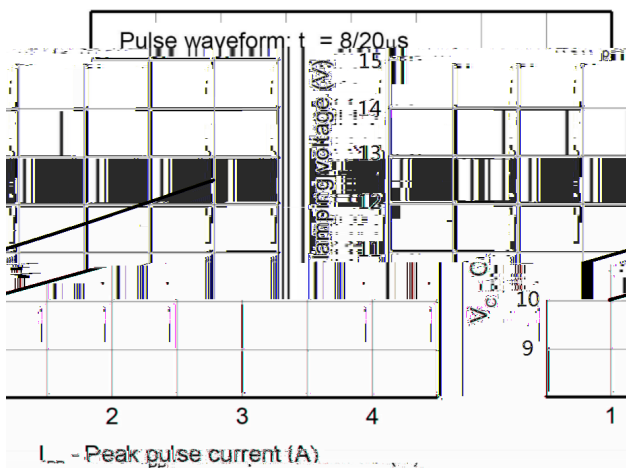
μ			
μ			
		$\pm$	
		$\pm$	

		$\pm$			$\pm$	
		μ				
		μ				

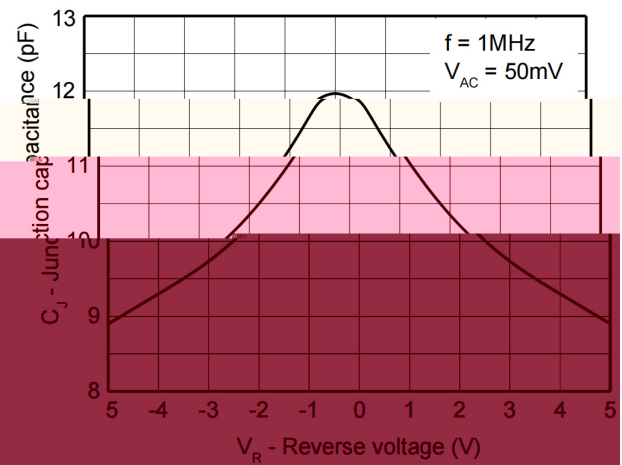


8/20-μs waveform per IEC61000-4-5

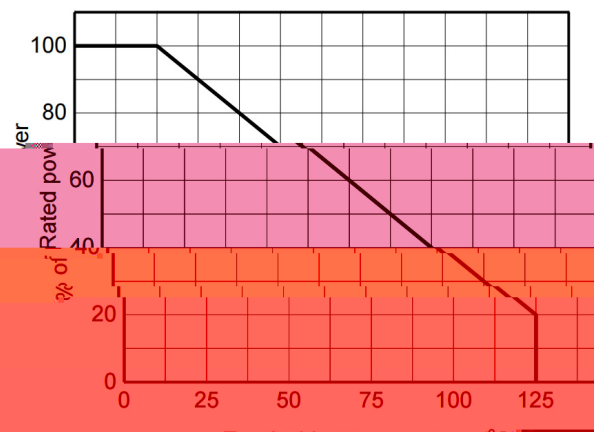
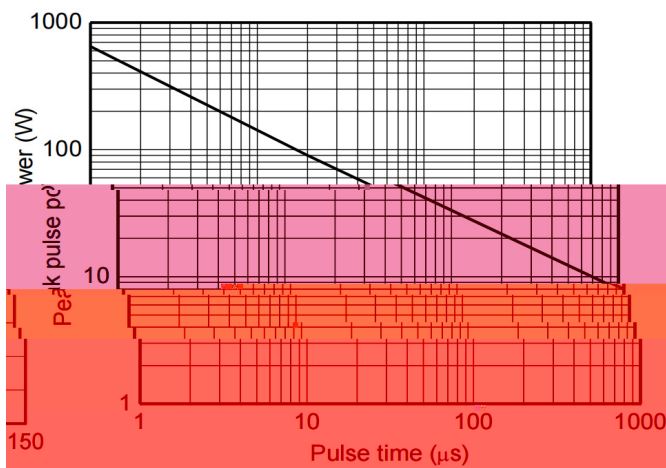
Contact discharge current waveform per IEC61000-4-2

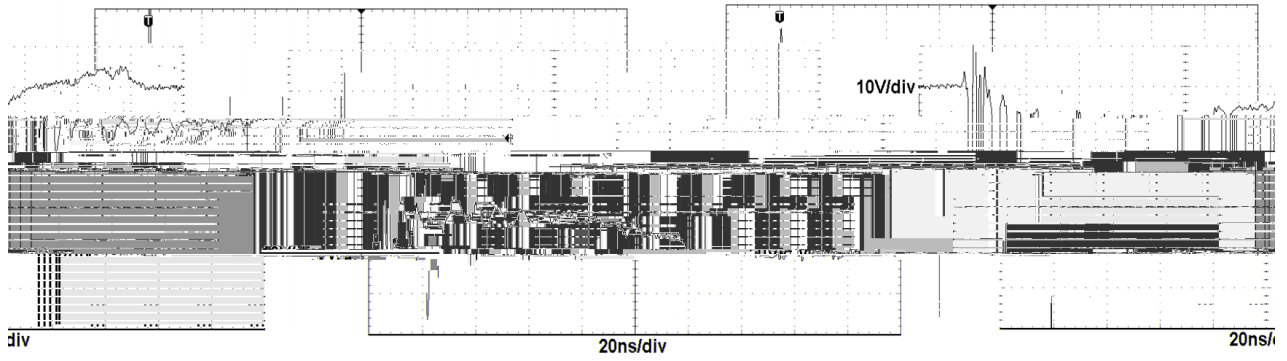


Clamping voltage vs. Peak pulse current



Capacitance vs. Reverse voltage





ping

ESD clamping

ESD clamping

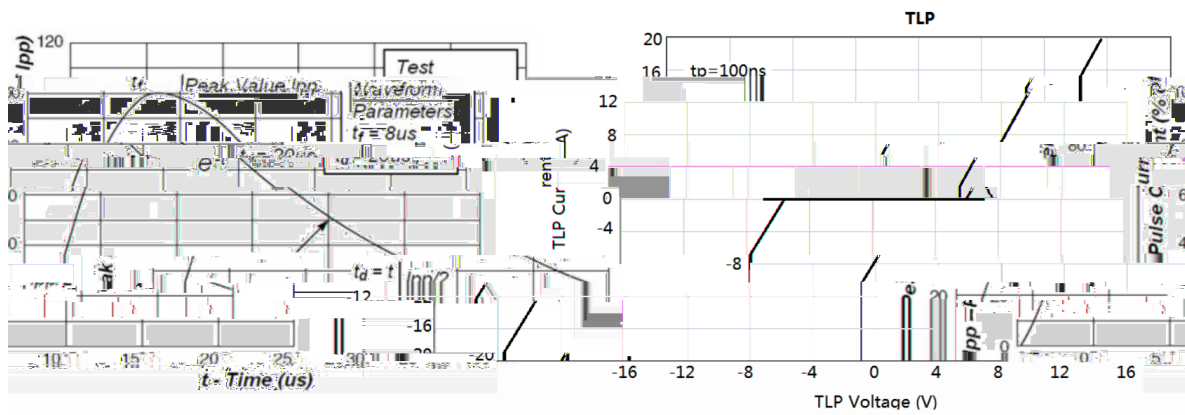
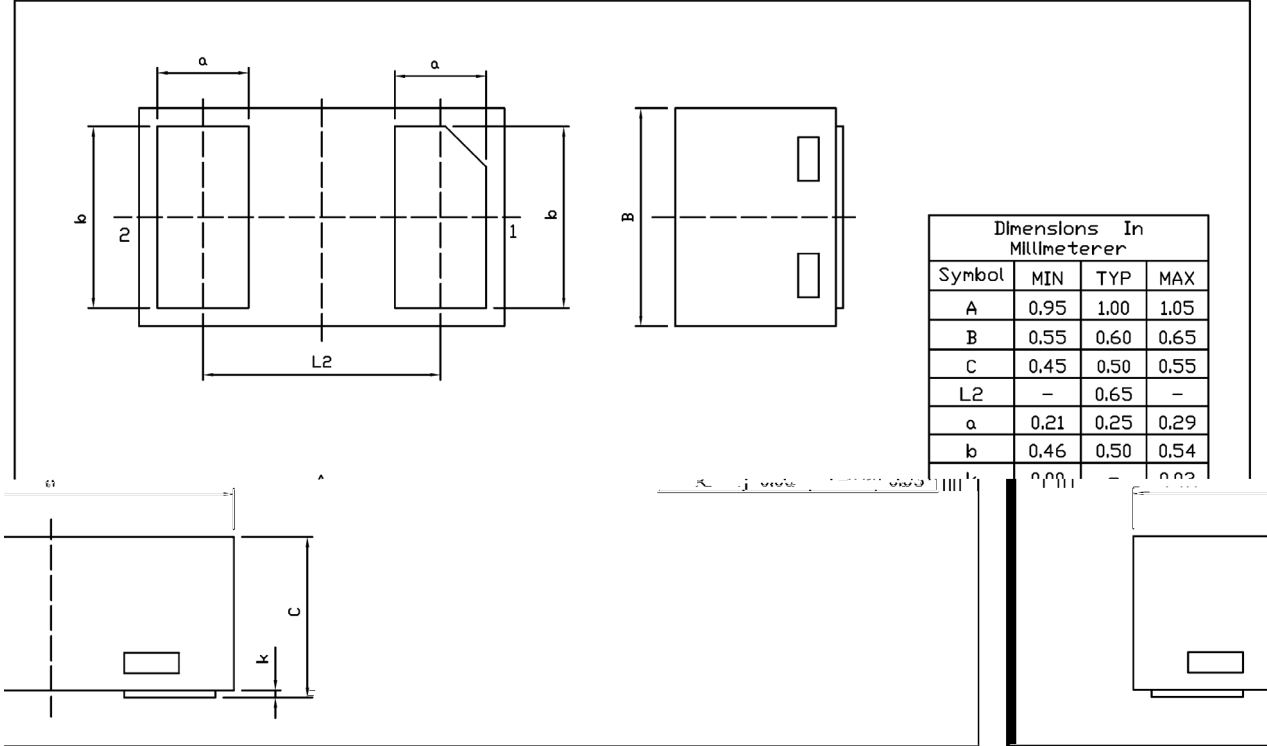


Fig3. Pulse_Waveform

Fig4.TLP Measurement

DFN1006-2L

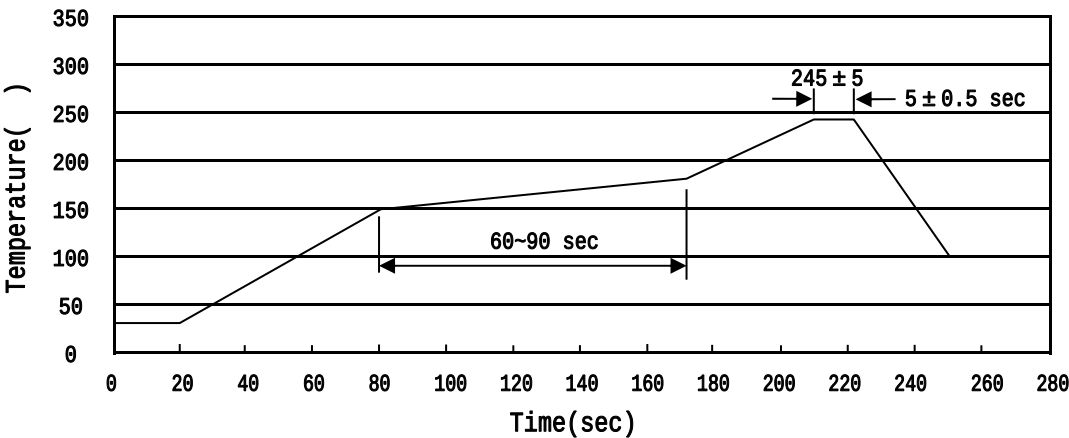
Unit:mm



Rev.01 202108



Temperature Profile for IR Reflow Soldering(Pb-Free)



	Units/Reel /	Reels/Inner Box /	Units/Inner Box /	Inner Boxes/Outer Box /	Units/Outer Box /	Reel	Inner Box	Outer Box